

Scalable Manufacturing of Flexible and Highly Conductive

Ti₃C₂T_x/PEDOT:PSS Thin Films for Electromagnetic Interference Shielding

Supplementary data

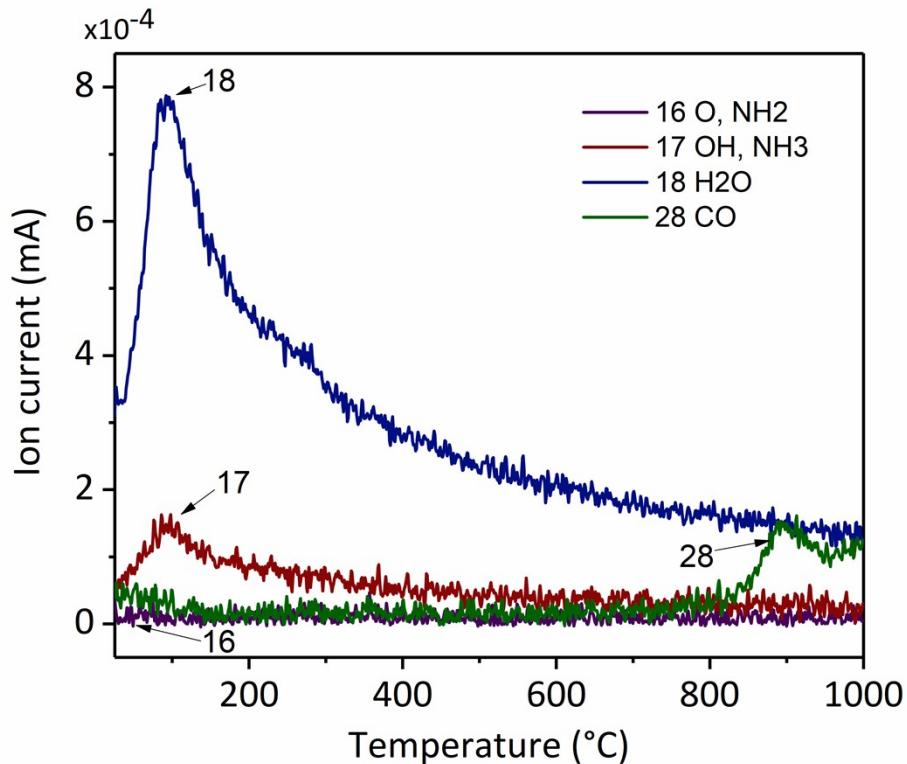


Figure S1. Sample mass spectrometry analysis of Ti₃C₂T_x.

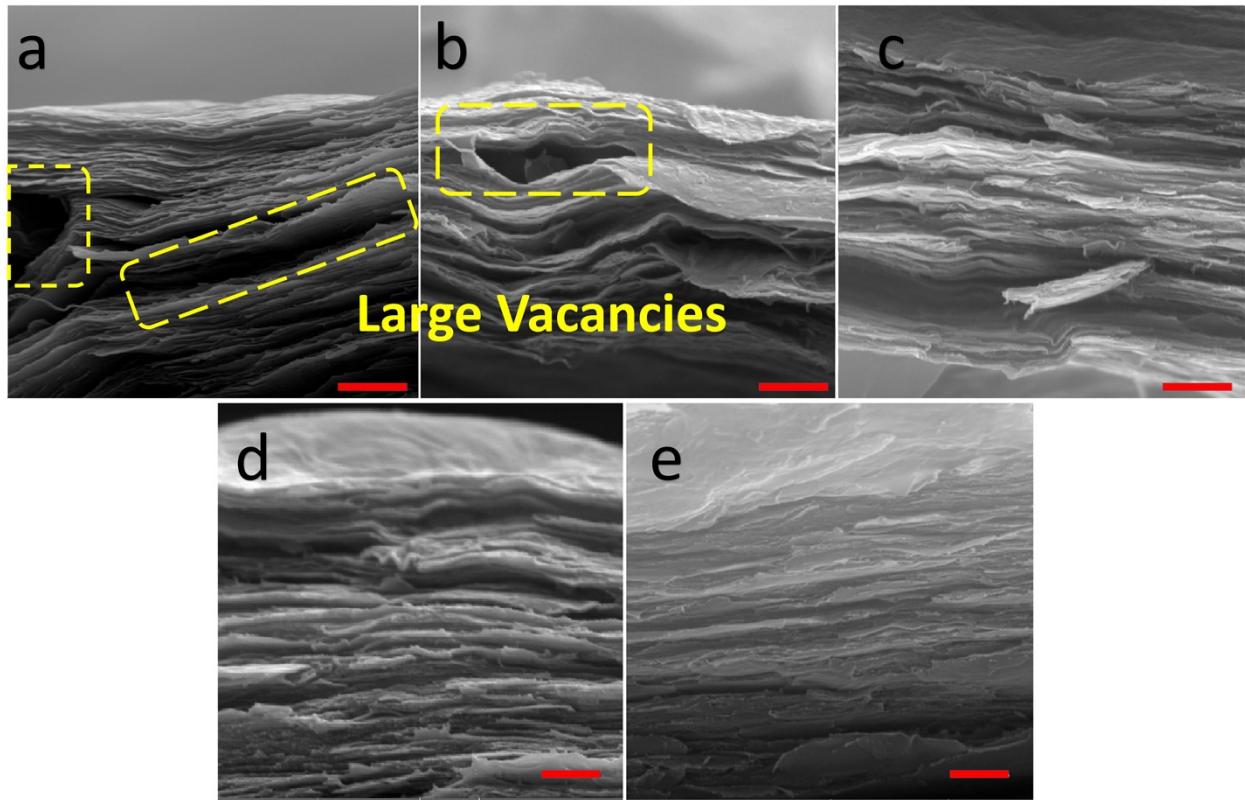


Figure S2. Cross-section SEM images of (a) the pristine $\text{Ti}_3\text{C}_2\text{T}_x$ and $\text{Ti}_3\text{C}_2\text{T}_x/\text{PEDOT:PSS}$ composite films containing (b) 10, (c) 25, (d) 35, and (e) 50 wt% of the polymer (scale is 2 μm). The large vacancies shown in Figures S3a-b were observed everywhere in the dried film.

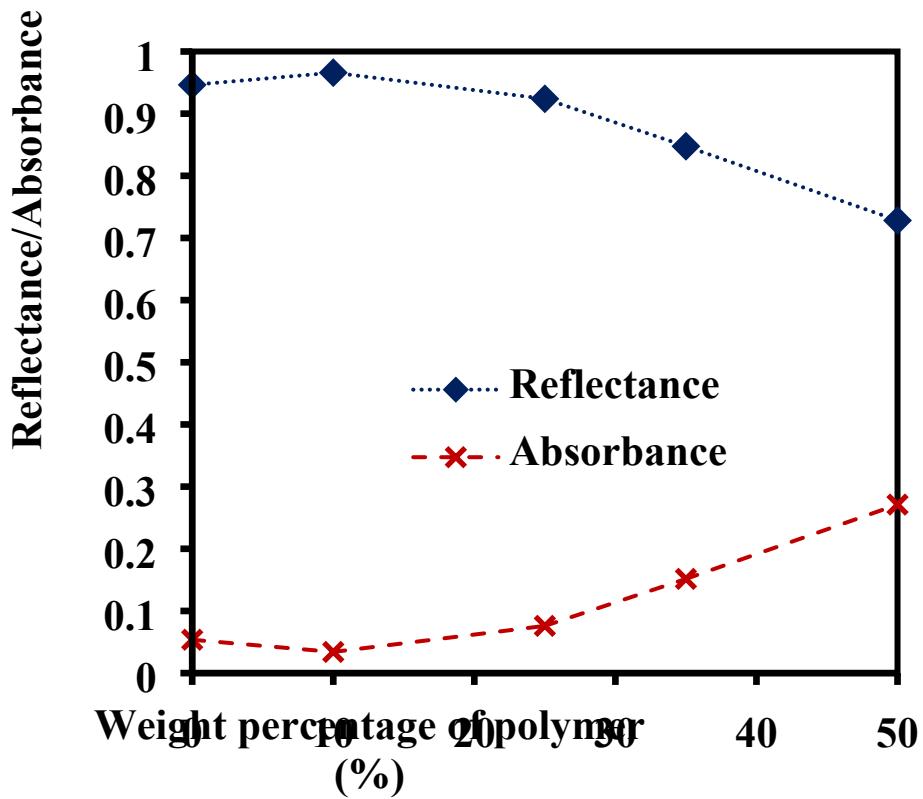


Figure S3. Reflectance and absorbance of pristine $\text{Ti}_3\text{C}_2\text{T}_x$ and the composite films that contained various concentrations of polymer.

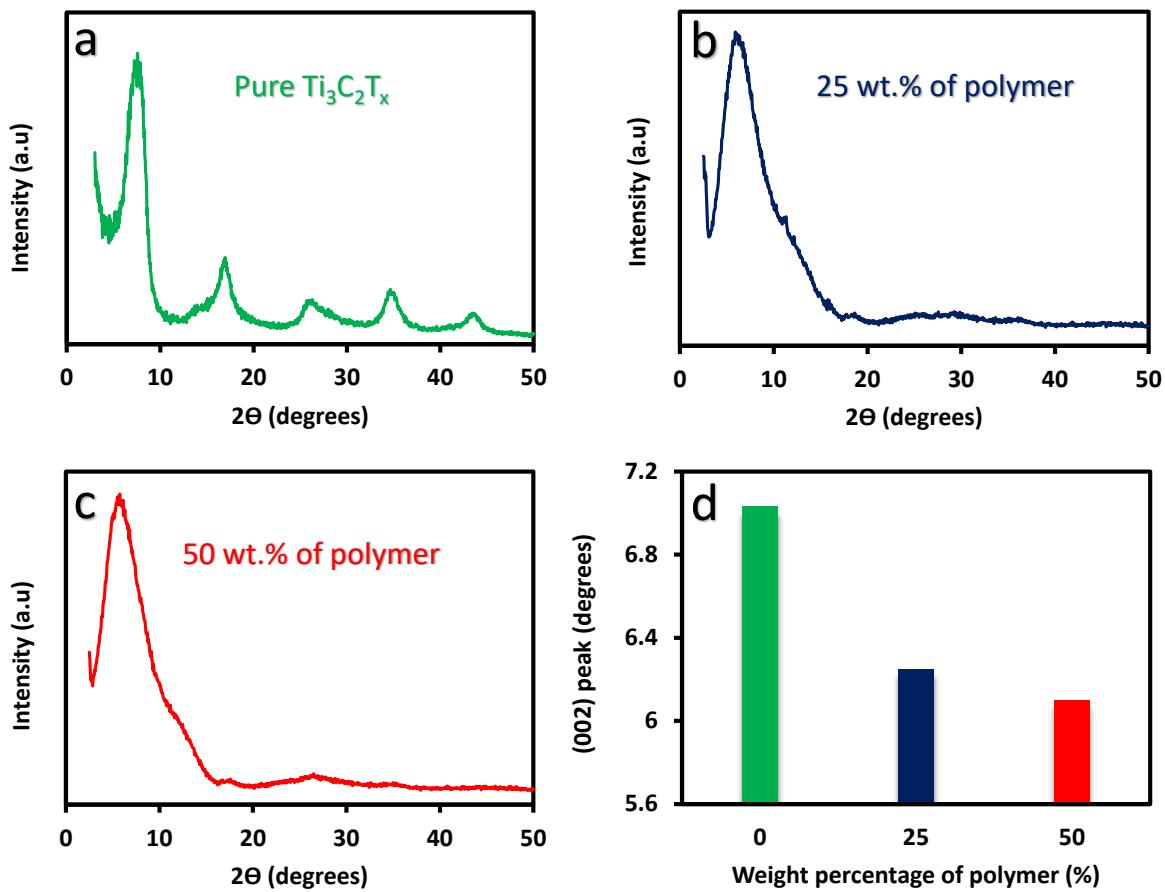


Figure S4. XRD patterns of (a) pure $\text{Ti}_3\text{C}_2\text{T}_x$ and the composite films that contained (b) 25 and (c) 50 wt.% of PEDOT:PSS. (d) Compression between the 002 peaks of the pristine $\text{Ti}_3\text{C}_2\text{T}_x$ and the composite films that contained various concentrations of polymer.

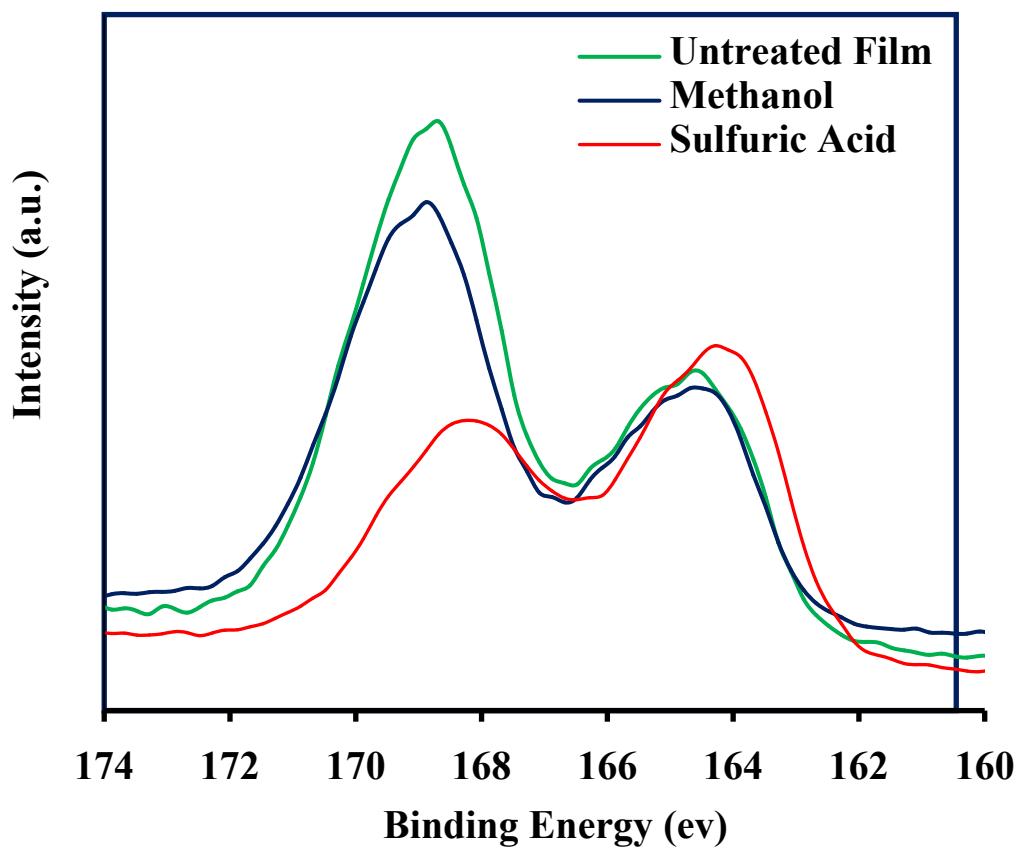


Figure S5. XPS results for the composite film containing 25 wt.% of PEDOT:PSS before and after post-treatment with sulfuric acid and methanol.

Table S1. Previous studies that used drop-casting or inkjet printing approach for PEDOT:PSS and its composites.

Material	Substrate	Method	Reference
Cu-Bi_{0.5}Sb_{1.5}Te₃ /PEDOT:PSS	Silicon dioxide (Activated by plasma)	Drop-casting	¹
PEDOT:PSS	Glass (Activated by UV/ozone)	Drop-casting	²
PEDOT:PSS/ethanol, and Graphene dots (GDs)/ PEDOT:PSS/ethanol	Fluorine-doped SnO ₂	Drop-casting	³
SnSe/PEDOT:PSS/ dimethyl sulfoxide (DMSO)	Glass	Drop-casting	⁴
PEDOT:PSS coated Te nanorod/ PEDOT:PSS	Glass	Drop-casting	⁵
Bi₂Te₃ nanosheet/PEDOT: PSS	Glass	Drop-casting	⁶
PEDOT: PSS	Silicon	Drop-casting	⁷
PEDOT: PSS	Glass wafer	Drop-casting	⁸
PEDOT: PSS	Silicon dioxide (Activated by plasma)	Drop-casting	⁹
PEDOT: PSS	Glass	Drop-casting	¹⁰
DMSO/PEDOT:PSS	Polydimethylsiloxane (PDMS)	Drop-casting	¹¹
PEDOT:PSS)/waterborne polyurethane (WPU)/ Carbon nanocoils (CNCs)	Glass or elastomeric substrates (Activated by plasma)	Drop-casting	¹²
PEDOT:PSS/ single-walled carbon nanotubes (SWCNTs)	Polyimide	Drop-casting	¹³
DMSO/PEDOT:PSS and ethylene glycol (EG)/ PEDOT:PSS	Polypropylene, glass, and poly(ethyleneterephthalate) (PET)	Drop-casting	¹⁴
PEDOT:PSS/SWCNTs/ DMSO	Glass	Drop-casting	¹⁵
Bi₂Te₃ nanosheet/PEDOT: PSS	Glass	Drop-casting	¹⁶
Cellulose/PEDOT:PSS/DMSO/glycerol	Glass	Drop-casting	¹⁷
PEDOT: PSS	Glass	Drop-casting	¹⁸
PEDOT: PSS/DMSO	Glass (Activated by aqua regia)	Drop-casting	¹⁹
Graphene oxide (GO)/PEDOT:PSS/DMSO	Glass (Activated with a mixture of concentrated sulfuric acid and hydrogen peroxide)	Drop-casting	²⁰
PEDOT:PSS/ CNTs	Polyimide	Drop-casting	²¹
PEDOT: PSS/DMSO	Glass	Drop-casting	²²
PEDOT: PSS	Glass	Drop-casting	²³
Ag₂Se NW/PEDOT:PSS	Glass	Drop-casting	²⁴
PEDOT:PSS/ GDs	Fluorine-doped SnO ₂	Drop-casting	²⁵
PEDOT-PSS/SWCNTs	PET	Inkjet printing	²⁶
PEDOT-PSS/vegetal glycerol	Polyimide	Inkjet printing	²⁷
PEDOT:PSS/DMSO	Pre-treated polyethylene naphthalate	Inkjet printing	²⁸
PEDOT:PSS	Polyimide (Activated by plasma)	Inkjet printing	²⁹
PEDOT:PSS	PET	Inkjet printing	³⁰
PEDOT-PSS/ ethanol/ diethylene glycol	Polyimide (Activated by plasma)	Inkjet printing	³¹

Table S2. Average static, advancing, and receding contact angles of water on the polycarbonate sheet.

	Average static contact angle	Average advancing contact angle	Average receding contact angle
Before treatment	81.6	89.2	69.6
After treatment for 30 min	24.2	28.6	19.9

Table S3. Average static, advancing, and receding contact angles of the aqueous solution of $\text{Ti}_3\text{C}_2\text{T}_x$ or $\text{Ti}_3\text{C}_2\text{T}_x/\text{PEDOT:PSS}$ (25 wt. %) on activated polycarbonate sheet.

	Average static contact angle	Average advancing contact angle	Average receding contact angle
$\text{Ti}_3\text{C}_2\text{T}_x$	17.3	21.1	14.2
$\text{Ti}_3\text{C}_2\text{T}_x/\text{PEDOT:PSS}$ (25 wt. %)	15.9	19.3	0

Table S4. Previous studies of thickness, conductivity, SE_T , and specific EMI shielding effectiveness of various nanocomposites.

Material	Thickness (mm)	Conductivity (σ cm $^{-1}$)	SE_T (dB)	$\text{SE}_T/\text{Density}/\text{thickness}$ (dB cm 2 g $^{-1}$)	Reference
$\text{Ti}_3\text{C}_2\text{T}_x/\text{PEDOT:PSS}$	0.011	340.5	42.1	19498	³²
$\text{Ti}_2\text{CT}_x/\text{Polyvinyl alcohol (PVA)}$	0.1	2.0×10^{-4}	26	5136	³³
$\text{Ti}_3\text{C}_2\text{T}_x/\text{Cellulose nanofiber (CNF)}$	0.035	1.43	39.6	7029	³⁴
$\text{Ti}_3\text{C}_2\text{T}_x/\text{Silver nanowires (AgNW)/ Nanocellulose (NC)}$	0.0169	300	42.74	16724	³⁵
$\text{Ti}_3\text{C}_2\text{T}_x/\text{Aramid nanofibers (ANF)}$	0.012	-	34.71	21971	³⁶
$\text{Ti}_3\text{C}_2\text{T}_x/\text{PVA}$	0.027	7.16	44.4	9343	³⁷
$\text{Polystyrene}/\text{Graphene}$	2.5	1.25	29	322	³⁸
$\text{Poly(3-hydrobutyrate-co-3-hydroxyvalerate) (PHBV)}/\text{AgNW}$	0.018	-	45.9	19678	³⁹
$\text{Ti}_3\text{C}_2\text{T}_x/\text{Polyacrylonitrile (PAN)}/\text{TiO}_2$	0.045	92.68	32	4085	⁴⁰
$\text{Ti}_3\text{C}_2\text{T}_x/\text{rGO}/\text{Epoxy}$	2	6.95	56.4	9400	⁴¹
$\text{Graphene}/\text{PEDOT:PSS}$	0.8	6.84	70	841	⁴²
$\text{V}_2\text{O}_5/\text{Polyaniline (PANI)}$	6	0.016	34.7	2770.3	⁴³
$\text{Ti}_3\text{C}_2\text{T}_x/\text{AgNW/CNF}$	0.035	373.78	59.7	10647	⁴⁴
$\text{Ti}_3\text{C}_2\text{T}_x/\text{Xanthan}$	0.00684	115.29	34.1	14,490	⁴⁵
$\text{Poly vinylidene fluoride (PVDF)}/\text{MWCNT}$	0.9	0.074	32	259	⁴⁶
$\text{Graphene}/\text{PMMA}$	0.24	3.11	19	1042	⁴⁷

Ti₃C₂T_x/PANI	0.376	3.25	35.3	1700	48
Poly(oxymethylene) (POM)/ MWCNT	2	3.33	58.6	344.4	49
Ti₃C₂T_x/CNF	0.047	7.39	24	2647	50
MWCNT/Polycarbonate	2.16	3	39	164	51
Ti₃C₂T_x/PEDOT:PSS	0.007	2900 ± 400	55.42	38079	This work

Table S5. Compositions of the Ti₃C₂T_x MXene and Ti₃C₂T_x MXene/PEDOT:PSS solutions used for drop-casting. One mL of each of the solutions was used for covering 9 cm² of polycarbonate sheet.

Sample name	PEDOT:PSS content (mg)	Ti ₃ C ₂ T _x MXene content (mg)	Water content (mL)
Pure Ti₃C₂T_x	-	15	1
10 wt.%	1.5	13.5	
25 wt.%	3.75	11.25	
35 wt.%	5.25	9.75	
50 wt.%	7.5	7.5	

Equations

1. The EMI reflection loss is calculated using:

$$SE_R = 168 + 10 \log \left(\frac{\sigma}{\mu f} \right) = 10 \log \left(\frac{1}{1 - R} \right) \quad (S1)$$

where σ is the conductivity, μ is the magnetic permeability of the shield relative to air, and f is the frequency in Hz and R is the reflectance.

2. The EMI absorption loss:

$$SE_A = 8.68t \left(\sqrt{\frac{\sigma \omega \mu}{2}} \right) = 8.68 \frac{t}{\delta} = 10 \log \left(\frac{1 - R}{T} \right) \quad (S2)$$

where t is the thickness of the shield, ω is the angular frequency in rad/s, δ is the skin depth of the shield, and T is the transmittance.

3. Reflectance (R):

$$R = S_{11}^2 \quad (S3)$$

where S_{11} is the reflected voltage magnitude divided by the incident voltage magnitude in port 1.

4. Transmittance (T):

$$T = S_{21}^2 \quad (S4)$$

where S_{21} is the transmitted voltage magnitude from port 1 to port 2 divided by the incident voltage magnitude in port 1.

5. Absorbance (A):

$$A = 1 - R - T \quad (S5)$$

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